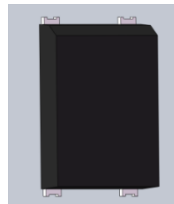


2.5A SURFACE MOUNT FAST GLASS PASSIVATED BRIDGE RECTIFIER
NEW PRODUCT
Product Summary (@ $T_A = +25^\circ\text{C}$)

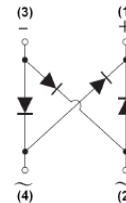
V_{RRM} (V)	I_O (A)	V_{FM} (V)	I_R (μA)
1000,800,600, 400,200,100	2.5	1.3	5

Description and Applications

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.



Top View



Internal Schematic

Features and Benefits

- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- Fast Recovery Time for Higher Efficiency
- Low Leakage Current
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- Surge Overload Rating to 75A Peak
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

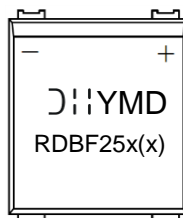
Mechanical Data

- Case: DBF
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 **(e3)**
- Polarity: As Marked on Body
- Weight: 0.02 grams (Approximate)

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RDBF2510-13	Commercial	DBF	3,000/Tape & Reel
RDBF258-13	Commercial	DBF	3,000/Tape & Reel
RDBF256-13	Commercial	DBF	3,000/Tape & Reel
RDBF254-13	Commercial	DBF	3,000/Tape & Reel
RDBF252-13	Commercial	DBF	3,000/Tape & Reel
RDBF251-13	Commercial	DBF	3,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information


RDBF25x(x) = Product Type Marking Code
 YMD = Manufacturers' Code Marking
 YMD = Date Code Marking
 Y = Last Digit of Year (ex: 8 = 2018)
 M = See Month/Code Table Below
 D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings and Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

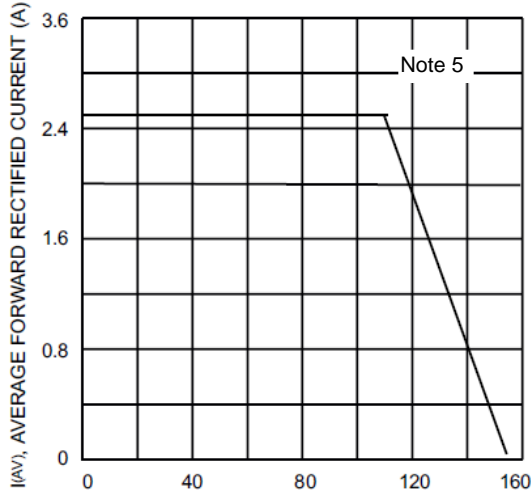
Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	RDBF251	RDBF252	RDBF254	RDBF256	RDBF258	RDBF2510	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Working Peak Reverse Voltage	V _{RWM}							
DC Blocking Voltage	V _R							
RMS Reverse Voltage	V _{R(RMS)}	70	140	280	420	560	700	V
Average Rectified Output Current (Note 5) @ T _C = +110°C	I _O	2.5						A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	75						A
I ² t Rating for Fusing (1ms < t < 8.3ms)	I ² t	23.34						A ² S
Max Forward Voltage (Per Element) @ I _F =2.5A	V _{FM}	1.3						V
Maximum Reverse Recovery Time (Note 7)	t _{RR}	150			250	500		ns
Peak Reverse Current @ T _A =+25°C	I _R	5.0						μA
At Rated DC Blocking Voltage @ T _A =+125°C (Note 8)	I _R	500						μA
Total Capacitance (Per Element) (Note 9)	C _T	30						pF

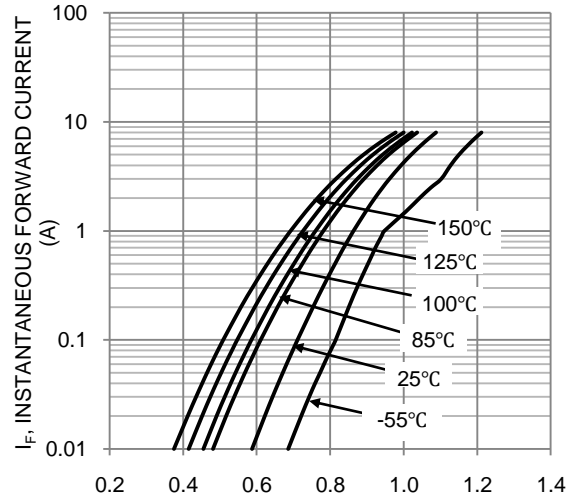
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element)	R _{θJA}	35	°C/W
Typical Thermal Resistance, Junction to Case (Per Element)	R _{θJC}	7.8	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

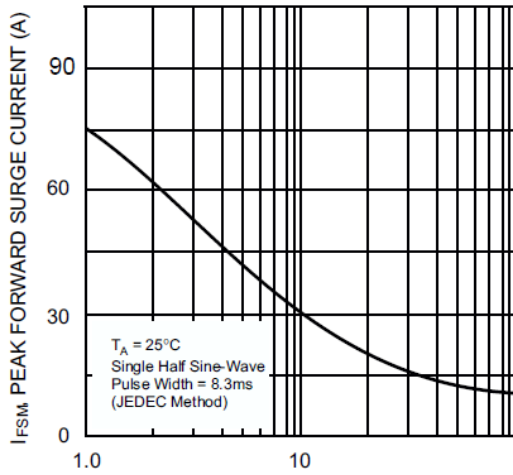
- Notes:
- Device mounted on glass epoxy PC board with 1.3mm² solder pad.
 - Device mounted on glass epoxy substrate with 1oz/ft², 30mmx30mm copper pad per pin.
 - Measured with I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A.
 - Short duration pulse test used to minimize self-heating effect.
 - Measured with V_R = 4.0VDC, f = 1MHz



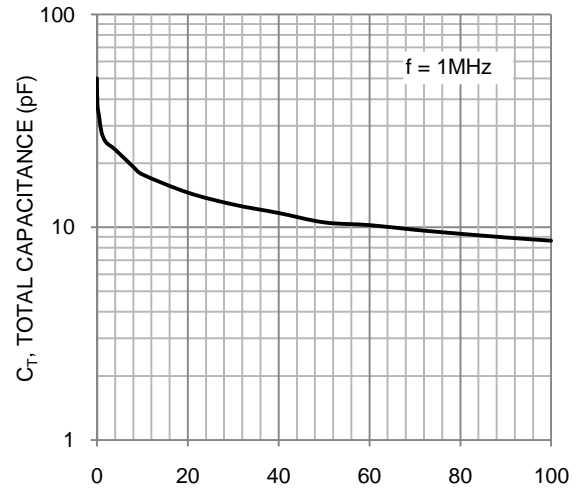
T_C , CASE TEMPERATURE (°C)
Fig. 1 Output Current Derating Curve



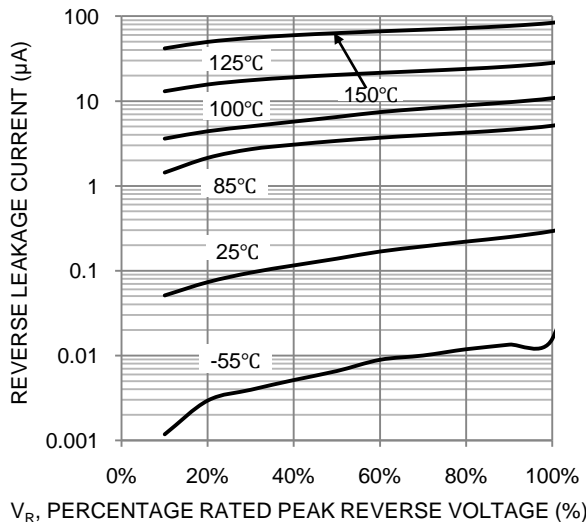
I_F , INSTANTANEOUS FORWARD CURRENT (A)
 V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics (Per Leg)



I_{FSM} , PEAK FORWARD SURGE CURRENT (A)
NUMBER OF CYCLES AT 60 Hz
Fig. 3 Maximum Peak Forward Surge Current (per leg)



C_T , TOTAL CAPACITANCE (pF)
 V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Junction Capacitance



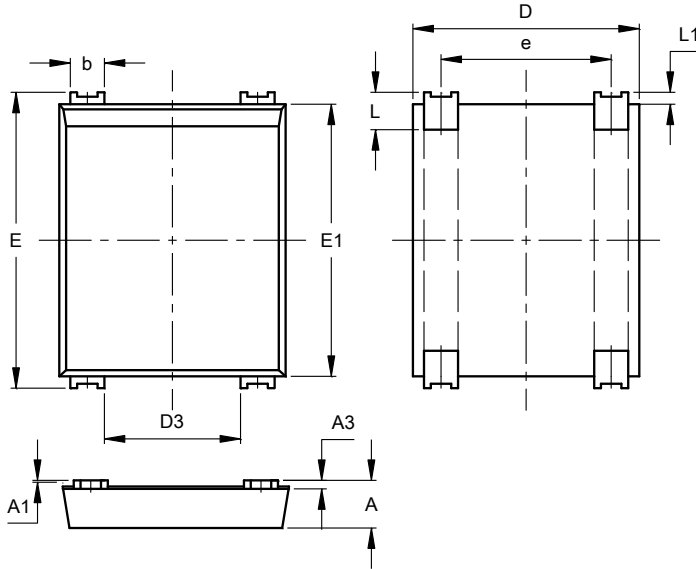
REVERSE LEAKAGE CURRENT (μ A)
 V_R , PERCENTAGE RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typical Reverse Characteristics

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

NEW PRODUCT

DBF

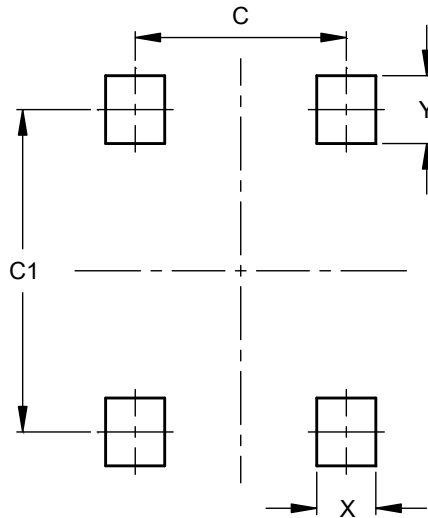


DBF			
Dim	Min	Max	Typ
A	1.30	1.50	--
A1	0.04	0.12	--
A3	0.15	0.35	--
b	0.80	1.20	--
D	6.45	6.85	--
D3	3.80	4.20	--
E	8.50	8.90	--
E1	7.80	8.20	--
e	4.80	5.20	--
L	0.80	1.40	--
L1	0.30	0.40	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

DBF



Dimensions	Value (in mm)
C	5.00
C1	7.60
X	1.40
Y	1.60